

Product / Package Information

Package	SSOP
Body Size	5.3 mm
LeadCount	24
Terminal Finish	100Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.49 E-02	86.20	862000	49.08	490805
Thermosets	Epoxy resin	Proprietary	8.25 E-03	7.50	75000	4.27	42703
Thermosets	Phenol Novolac	9003-35-4	4.40 E-03	4.00	40000	2.28	22775
Other inorganic materials	Antimony Trioxide	1309-64-4	1.65 E-03	1.50	15000	0.85	8541
Thermosets	Brominated Resin	40039-93-8	5.50 E-04	0.50	5000	0.28	2847
Other inorganic materials	Carbon Black	1333-86-4	3.30 E-04	0.30	3000	0.17	1708
Subtotal			1.10 E-01	100	1000000	56.94	569379
Leadframe							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.44 E-02	97.50	975000	38.49	384936
Copper & its alloys	Iron	7439-89-6	1.79 E-03	2.35	23500	0.93	9278
Copper & its alloys	Zinc	7440-66-6	9.16 E-05	0.12	1200	0.05	474
Copper & its alloys	Phosphorus	7723-14-0	2.29 E-05	0.03	300	0.01	118
Subtotal			7.63 E-02	100.00	1000000	39.48	394806
Internal Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.71 E-04	100.0	1000000	0.40	3988
External Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.04 E-03	100.0	1000000	2.09	20900
Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.20 E-04	99.99	1000000	0.11	1138
Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.58 E-03	100.0	1000000	0.82	8185
Die Attach							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.48 E-04	80	800000	0.13	1283
Thermosets	Epoxy Resin	Proprietary	4.65 E-05	15	150000	0.02	241
Others	Curing agent & hardener	Proprietary	1.55 E-05	5	50000	0.01	80
Subtotal			3.10 E-04	100	1000000	0.16	1604
Package Totals			Weight (g)	Percentage (%)		PPM	
			1.93 E-01	100.00		1000000	

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.



ADI Proprietary

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Package	SSOP
Body Size	5.3 mm
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Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.49 E-02	86.20	862000	49.08	490805
Thermosets	Epoxy resin	Proprietary	8.25 E-03	7.50	75000	4.27	42703
Thermosets	Phenol Novolac	9003-35-4	4.40 E-03	4.00	40000	2.28	22775
Other inorganic materials	Antimony Trioxide	1309-64-4	1.65 E-03	1.50	15000	0.85	8541
Thermosets	Brominated Resin	40039-93-8	5.50 E-04	0.50	5000	0.28	2847
Other inorganic materials	Carbon Black	1333-86-4	3.30 E-04	0.30	3000	0.17	1708
Subtotal			1.10 E-01	100	1000000	56.94	569379

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Copper & its alloys	Copper	7440-50-8	7.44 E-02	97.50	975000	38.49	384936
Copper & its alloys	Iron	7439-89-6	1.79 E-03	2.35	23500	0.93	9278
Copper & its alloys	Zinc	7440-66-6	9.16 E-05	0.12	1200	0.05	474
Copper & its alloys	Phosphorus	7723-14-0	2.29 E-05	0.03	300	0.01	118
Subtotal			7.63 E-02	100.00	1000000	39.48	394806

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.71 E-04	100.0	1000000	0.40	3988

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.43 E-03	85.0	850000	1.78	17765
Tin & its alloys	Lead	7439-92-1	6.06 E-04	15.0	150000	0.31	3135
Subtotal			4.04 E-03	100.0	1000000	2.09	20900

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.20 E-04	99.99	1000000	0.11	1138

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.58 E-03	100.0	1000000	0.82	8185

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Precious metals	Silver	7440-22-4	2.48 E-04	80	800000	0.13	1283
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Others	Curing agent & hardener	Proprietary	1.55 E-05	5	50000	0.01	80
Subtotal			3.10 E-04	100	1000000	0.16	1604

			Weight (g)	Percentage (%)		PPM
Package Totals			1.93 E-01	100.00		1000000

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